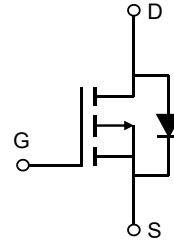


Description

Features

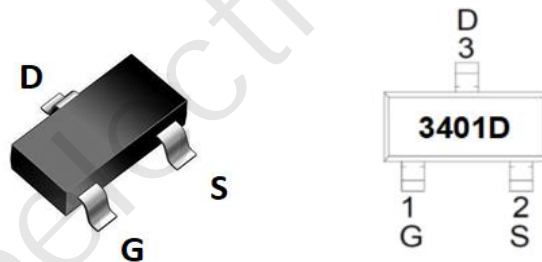
- -30V, -4.2A
 $R_{DS(ON)}$ Typ = 38mΩ @ $V_{GS} = -10V$
 $R_{DS(ON)}$ Typ = 46mΩ @ $V_{GS} = -4.5V$
 $R_{DS(ON)}$ Typ = 66mΩ @ $V_{GS} = -2.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMLBU3401D	3401D	SOT-23	TAPING	7"	3000	120000

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	-30	V
V_{GS}	Gate-to-Source Voltage	±12	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	-4.2
		$T_A = 100^\circ C$	-2.52
I_{DM}	Pulsed Drain Current ⁽¹⁾	-16.8	A
P_D	Power Dissipation	$T_A = 25^\circ C$	1.5
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽²⁾	83	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = -250μA, V _{GS} = 0V	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V	-	-	-1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-0.6	-0.95	-1.4	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = -10V, I _D = -2A	-	38	50	mΩ
		V _{GS} = -4.5V, I _D = -1A	-	46	60	mΩ
		V _{GS} = -2.5V, I _D = -1A	-	66	86	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance		-	510	-	pF
C _{oss}	Output Capacitance	V _{GS} = 0V, V _{DS} = -15V, f = 1MHz	-	54	-	pF
C _{riss}	Reverse Transfer Capacitance		-	47	-	pF
Q _g	Total Gate Charge		-	6	-	nC
Q _{gs}	Gate Source Charge	V _{GS} = 0 to -4.5V	-	1.4	-	nC
Q _{gd}	Gate Drain("Miller") Charge	V _{DS} = -15V, I _D = -3A	-	2	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime		-	10	-	ns
t _r	Turn-On Rise Time	V _{GS} = -4.5V, V _{DD} = -15V	-	80	-	ns
t _{d(off)}	Turn-Off DelayTime	I _D = -3A, R _{GEN} = 3Ω	-	120	-	ns
t _f	Turn-Off Fall Time		-	350	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-4.2	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-16.8	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -2A	-	-	-1.2	V
t _{rr}	Body Diode Reverse Recovery Time		-	35	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F = -3A, di/dt = 100A/us	-	4	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. R_{eJA} is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB
 3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

Test Circuit

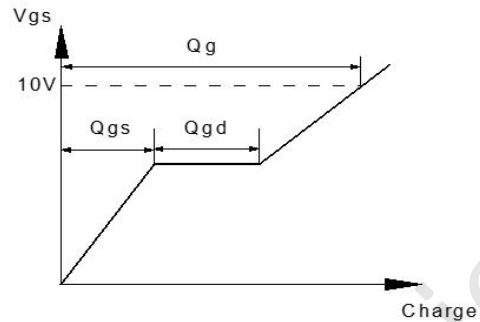
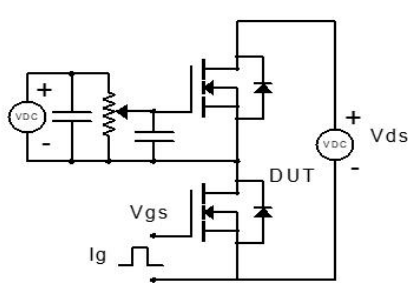


Figure 1: Gate Charge Test Circuit & Waveform

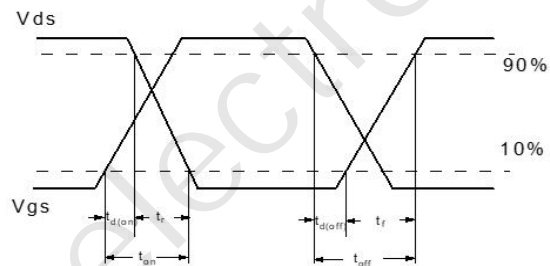
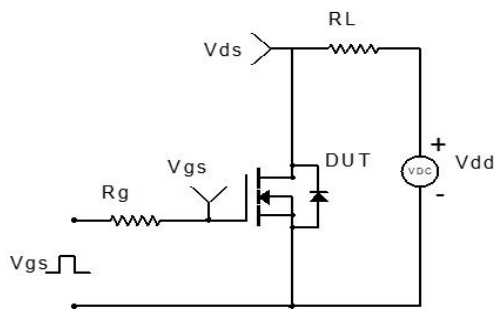


Figure 2: Resistive Switching Test Circuit & Waveform

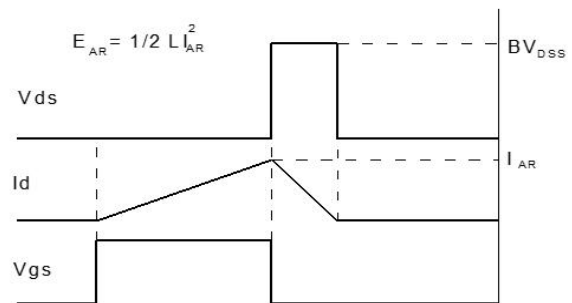
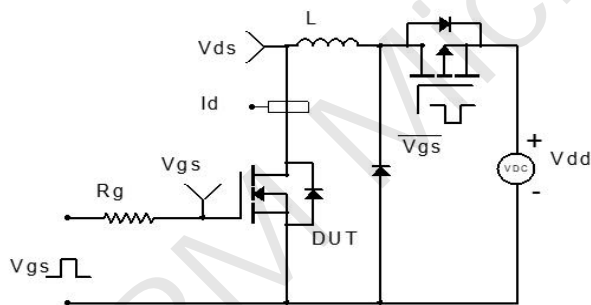


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

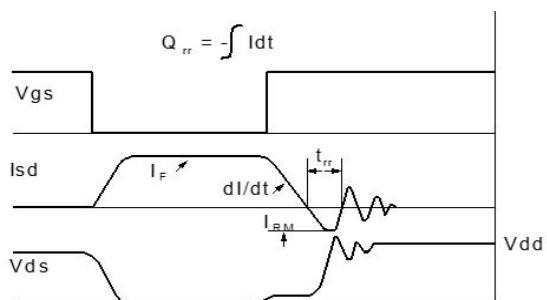
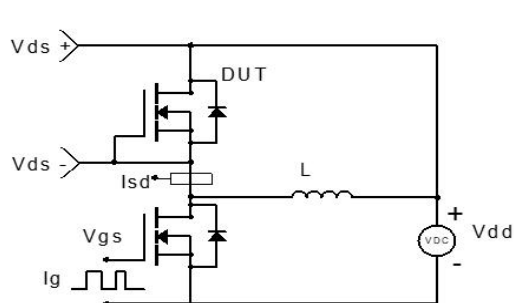
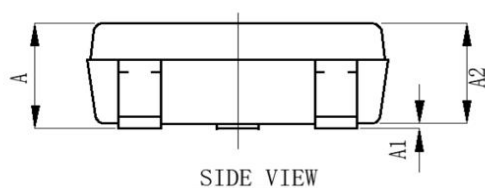
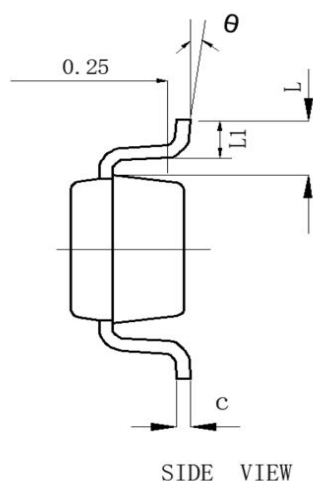
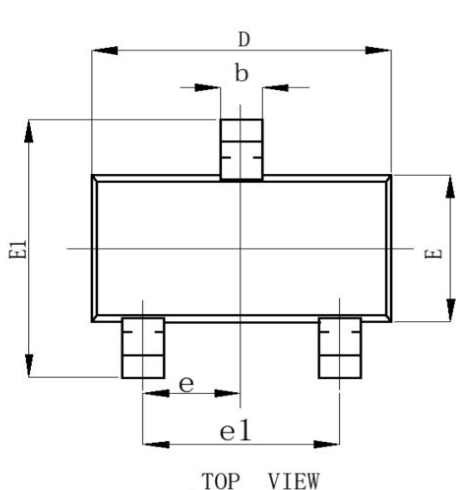


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOT-23)




COMMON DIMENSIONS In Millimeters		
SYMBOL	MIN	MAX
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
L	0.550 REF.	
θ	0°	8°
L1	0.300	0.500
e	0.950 TYP.	
e1	1.800	2.000

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